



# TG-S09AB

## Silicone Potting Compound

REACH Compliant RoHS Compliant

### Features

- Good thermal conductivity
- Protect based material with high hardness for support
- A:B=1:1
- Room temperature or heating curing

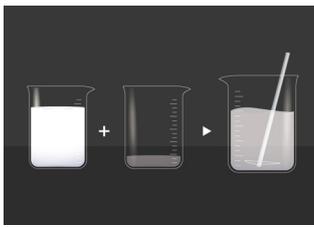
### Applications

Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

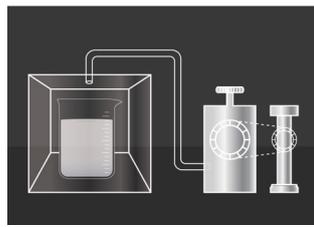
### Storage

Silicone Potting Compound has a shelf-life of twelve (12) months from the date of manufacture, as indicated by the lot number, when stored in the original, should be unopened container at or below 25° C.

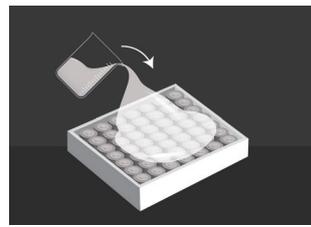
### Operation Manual



① Mix component A and B.



② Vacuum out air.

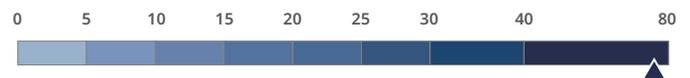
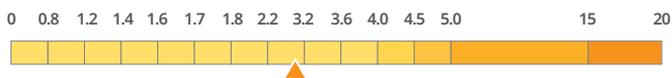


③ Pour potting compound.

### Properties

Thermal Conductivity : 2.8 W/mK

Hardness : 75 (Shore 00)



Properties	TG-S09AB	Unit	Tolerance	Test Method
Thermal Conductivity	2.8	W/mK	±10%	ASTM D5470
Color	Gray	-	-	Visual
Dielectric Breakdown Voltage	10	KV/mm	±10%	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	2.8	g/cm <sup>3</sup>	±10%	ASTM D792
Working Temperature	-25~+150	° C	-	-
Viscosity	1700~2300	Pa·s	-	ASTM D2393
Curing Time @25° C	18	Hrs	-	-
Curing Time @80° C	0.5	Hrs	-	-
Standard Format	1kg	Pot	-	-
Hardness	75	Shore 00	±10	ASTM D2240
Mixing Ratio	1:1	gram	-	-

- ▶ Component A is a mixed material of silicone and thermal conductive powder. It is normal to cause precipitation and stratification due to different density. Before use, please use a flat spatula or other stainless tools to evenly mix component A to achieve the best thermal conductivity.